

Is Now Part of



ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild guestions@onsemi.com.

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdf/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any EDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officer



May 2002 Revised June 2005

74LCXH16245

Low Voltage 16-Bit Bidirectional Transceiver with Bushold

General Description

The LCXH16245 contains sixteen non-inverting bidirectional buffers with 3-STATE outputs and is intended for bus oriented applications. The device is designed for low voltage (2.5V or 3.3V) $V_{\rm CC}$ applications with capability of interfacing to a 5V signal environment. The device is byte controlled. Each byte has separate control inputs which could be shorted together for full 16-bit operation. The T/\overline{R} inputs determine the direction of data flow through the device. The $\overline{\rm OE}$ inputs disable both the A and B Ports by placing them in a high impedance state.

The LCXH16245 data inputs include active bushold circuitry, eliminating the need for external pull-up resistors to hold unused or floating data inputs at a valid logic level.

The LCXH16245 is fabricated with an advanced CMOS technology to achieve high speed operation while maintaining CMOS low power dissipation.

Features

- 2.3V-3.6V V_{CC} specifications provided
- 4.5 ns t_{PD} max (V_{CC} = 3.3V), 20 μ A I_{CC} max
- Power-down high impedance outputs
- Bushold on inputs eliminates the need for external pull-up/pull-down resistors
- ± 24 mA output drive ($V_{CC} = 3.0V$)
- Implements patented noise/EMI reduction circuitry
- Latch-up performance conforms to the requirements of JESD78
- ESD performance:

Human body model > 2000V

Machine model > 200V

Also packaged in plastic Fine-Pitch Ball Grid Array (FBGA)

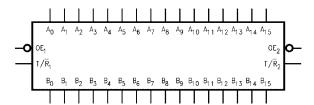
Ordering Code:

| Order Number | Package Number | Package Description |
|-----------------------------------|----------------|---|
| 74LCXH16245G (Note 1) (Note 2) | BGA54A | 54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide |
| 74LCXH16245MTD (Note 2) | MTD48 | 48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide |

Note 1: Ordering Code "G" indicates Trays.

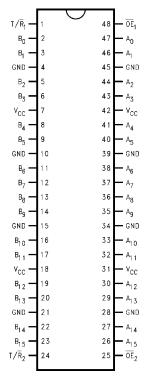
Note 2: Devices also available in Tape and Reel. Specify by appending the suffix letter "X" to the ordering code.

Logic Symbol

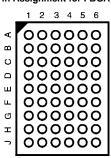


Connection Diagrams

Pin Assignment for SSOP and TSSOP



Pin Assignment for FBGA



(Top Thru View)

Pin Descriptions

| Pin Names | Description |
|--|--|
| \overline{OE}_n T/ \overline{R}_n | Output Enable Input |
| T/\overline{R}_n | Transmit/Receive Input |
| A ₀ -A ₁₅ B ₀ -B ₁₅ | Side A Inputs or 3-STATE Outputs (Bushold) |
| B ₀ -B ₁₅ | Side B Inputs or 3-STATE Outputs (Bushold) |

FBGA Pin Assignments

| | 1 | 2 | 3 | 4 | 5 | 6 |
|---|-----------------|-----------------|--------------------|-----------------|-----------------|-----------------|
| Α | B ₀ | NC | T/\overline{R}_1 | OE ₁ | NC | A ₀ |
| В | B ₂ | B ₁ | NC | NC | A ₁ | A ₂ |
| С | B ₄ | B ₃ | V _{CC} | V _{CC} | A ₃ | A ₄ |
| D | B ₆ | B ₅ | GND | GND | A ₅ | A ₆ |
| E | B ₈ | B ₇ | GND | GND | A ₇ | A ₈ |
| F | B ₁₀ | B ₉ | GND | GND | A ₉ | A ₁₀ |
| G | B ₁₂ | B ₁₁ | V _{CC} | V _{CC} | A ₁₁ | A ₁₂ |
| Н | B ₁₄ | B ₁₃ | NC | NC | A ₁₃ | A ₁₄ |
| J | B ₁₅ | NC | T/\overline{R}_2 | OE ₂ | NC | A ₁₅ |

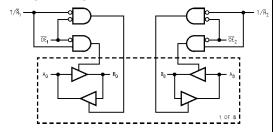
Truth Tables

| In | outs | Outroots. |
|-----------------|------------------|---|
| OE ₁ | T/R ₁ | Outputs |
| L | L | Bus B ₀ –B ₇ Data to Bus A ₀ –A ₇ |
| L | Н | Bus A ₀ -A ₇ Data to Bus B ₀ -B ₇ |
| Н | Х | HIGH Z State on A ₀ -A ₇ , B ₀ -B ₇ |

| Inp | outs | Outputs | |
|-----------------|------------------|--|--|
| OE ₂ | T/R ₂ | Outputs | |
| L | L | Bus B ₈ –B ₁₅ Data to Bus A ₈ –A ₁₅ | |
| L | Н | Bus B ₈ -B ₁₅ Data to Bus A ₈ -A ₁₅ Bus A ₈ -A ₁₅ Data to Bus B ₈ -B ₁₅ | |
| Н | Χ | HIGH Z State on A ₈ –A ₁₅ , B ₈ –B ₁₅ | |

H = HIGH Voltage Level

Logic Diagram



L = LOW Voltage Level
X = Immaterial
Z = High Impedance

Absolute Maximum Ratings(Note 3) Symbol Parameter Value Units Conditions -0.5 to +7.0 ٧ Supply Voltage V_{CC} ٧ DC Input Voltage -0.5 to V_{CC} + 0.5 V_{I} DC Output Voltage Vo -0.5 to +7.0 Output in 3-STATE ٧ Output in HIGH or LOW State (Note 4) -0.5 to $V_{CC} + 0.5$ DC Input Diode Current -50 $V_I < GND$ mΑ I_{IK} DC Output Diode Current -50 V_O < GND I_{OK} mΑ +50 $V_O > V_{CC}$ DC Output Source/Sink Current ±50 mΑ I_{O} I_{CC} DC Supply Current per Supply Pin ±100 mΑ DC Ground Current per Ground Pin ±100 I_{GND} Storage Temperature -65 to +150 T_{STG}

Recommended Operating Conditions (Note 5)

| Symbol | Parameter | | Min | Max | Units |
|----------------------------------|--|------------------------|-----|-----------------|-------|
| V _{CC} | Supply Voltage | Operating | 2.0 | 3.6 | V |
| | | Data Retention | 1.5 | 3.6 | v |
| V _I | Input Voltage | | 0 | V _{CC} | V |
| Vo | Output Voltage | HIGH or LOW State | 0 | V _{CC} | V |
| | | 3-STATE | 0 | V_{CC} | v |
| I _{OH} /I _{OL} | Output Current | $V_{CC} = 3.0V - 3.6V$ | | ±24 | |
| | | $V_{CC} = 2.7V - 3.0V$ | | ±12 | mA |
| | | $V_{CC} = 2.3V - 2.7V$ | | ±8 | |
| T _A | Free-Air Operating Temperature | | -40 | 85 | °C |
| Δt/ΔV | Input Edge Rate, V _{IN} = 0.8V–2.0V, V _{CC} = 3.0V | | 0 | 10 | ns/V |

Note 3: The Absolute Maximum Ratings are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the Absolute Maximum Ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

Note 4: I_O Absolute Maximum Rating must be observed.

Note 5: Floating or unused control inputs must be HIGH or LOW.

DC Electrical Characteristics

| Symbol | Parameter | | Conditions | V _{CC} | T _A = -40°C | C to +85°C | Units |
|-----------------|---------------------------|---------|--------------------------|-----------------|------------------------|------------|-------|
| | i diameter | | Conditions | (V) | (V) Min | Max | Onits |
| V _{IH} | HIGH Level Input Voltage | | | 2.3 – 2.7 | 1.7 | | V |
| | | | | 2.7 - 3.6 | 2.0 | | V |
| V _{IL} | LOW Level Input Voltage | | | 2.3 – 2.7 | | 0.7 | V |
| | | | | 2.7 - 3.6 | | 8.0 | V |
| V _{OH} | HIGH Level Output Voltage | | $I_{OH} = -100 \mu A$ | 2.3 - 3.6 | V _{CC} - 0.2 | | |
| | | | I _{OH} = -8 mA | 2.3 | 1.8 | | |
| | | | I _{OH} = -12 mA | 2.7 | 2.2 | | V |
| | | | I _{OH} = -18 mA | 3.0 | 2.4 | | |
| | | | I _{OH} = -24 mA | 3.0 | 2.2 | | |
| V _{OL} | LOW Level Output Voltage | | I _{OL} = 100 μA | 2.3 - 3.6 | | 0.2 | |
| | | | I _{OL} = 8mA | 2.3 | | 0.6 | |
| | | | I _{OL} = 12 mA | 2.7 | | 0.4 | V |
| | | | I _{OL} = 16 mA | 3.0 | | 0.4 | |
| | | | I _{OL} = 24 mA | 3.0 | | 0.55 | |
| I | Input Leakage Current | Data | $V_I = V_{CC}$ or GND | 2.3 - 3.6 | | ±5.0 | |
| | | Control | $O \le V_1 \le 5.5$ | 2.3 - 3.6 | | ±5.0 | μА |

DC Electrical Characteristics (Continued)

| Symbol | Parameter | Conditions | V _{CC} | T _A = -40°C to +85°C | | Units |
|----------------------|---------------------------------------|---|-----------------|---------------------------------|------|--------|
| | | Conditions | (V) | Min | Max | Ullits |
| I _{I(HOLD)} | Bushold Input Minimum | V _{IN} = 0.7V | 2.3 | 45 | | |
| | Drive Hold Current | V _{IN} = 1.7V | 2.3 | -45 | | ^ |
| | | $V_{IN} = 0.8V$ | 3.0 | 75 | | μА |
| | | V _{IN} = 2.0V | 3.0 | -75 | | |
| I _{I(OD)} | Bushold Input Over-Drive | (Note 6) | 2.7 | 300 | | |
| | Current to Change State | (Note 7) | 2.1 | -300 | | ^ |
| | | (Note 6) | 3.6 | 450 | | μА |
| | | (Note 7) | 3.6 | -450 | | |
| l _{oz} | 3-STATE I/O Leakage | $V_O = V_{CC}$ or GND | 2.3 - 3.6 | | ±5.0 | μΑ |
| I _{OFF} | Power-Off Leakage Current | V_I or $V_O = 5.5V$ | 0 | | 10 | μΑ |
| Icc | Quiescent Supply Current | V _I = V _{CC} or GND | 2.3-3.6 | | 20 | μА |
| Δl _{CC} | Increase in I _{CC} per Input | V _{IH} = V _{CC} -0.6V | 2.3-3.6 | | 500 | μА |

Note 6: An external driver must source at least the specified current to switch from LOW-to-HIGH.

AC Electrical Characteristics

| | | | T _A | = -40°C to + | 85°C, R _L = 50 | 10Ω | | |
|------------------|----------------------------------|-----------------------|----------------|-------------------|---------------------------|----------------------|-----------|-------|
| Cumbal | Parameter | V _{CC} = 3.3 | 3V ± 0.3V | V _{CC} = | 2.7V | V _{CC} = 2. | 5V ± 0.2V | Units |
| Symbol | Parameter | C _L = | 50 pF | C _L = | 50 pF | C _L = | 30 pF | Units |
| | | Min | Max | Min | Max | Min | Max | |
| t _{PHL} | Propagation Delay | 1.0 | 4.5 | 1.0 | 5.2 | 1.0 | 5.4 | no |
| t _{PLH} | A_n to B_n or B_n to A_n | 1.0 | 4.5 | 1.0 | 5.2 | 1.0 | 5.4 | ns |
| t _{PZL} | Output Enable Time | 1.0 | 6.5 | 1.0 | 7.2 | 1.0 | 8.5 | ns |
| t_{PZH} | | 1.0 | 6.5 | 1.0 | 7.2 | 1.0 | 8.5 | 115 |
| t _{PLZ} | Output Disable Time | 1.0 | 6.4 | 1.0 | 6.9 | 1.0 | 7.7 | no |
| t_{PHZ} | | 1.0 | 6.4 | 1.0 | 6.9 | 1.0 | 7.7 | ns |
| toshl | Output to Output Skew (Note 8) | | 1.0 | | | | | ns |
| toslh | | | 1.0 | | | | | 115 |

Note 8: Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (toshic) or LOW-to-HIGH (toslih). Parameter guaranteed by design.

Dynamic Switching Characteristics

| Symbol | Parameter | Conditions | v _{cc} (v) | T _A = 25°C | Units |
|------------------|---|---|------------------------|-----------------------|-------|
| V _{OLP} | Quiet Output Dynamic Peak V _{OL} | $C_L = 50 \text{ pF}, V_{IH} = 3.3V, V_{IL} = 0V$ | 3.3 | 0.8 | V |
| | | $C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$ | 2.5 | 0.6 | V |
| V _{OLV} | Quiet Output Dynamic Valley V _{OL} | $C_L = 50 \text{ pF}, V_{IH} = 3.3 \text{V}, V_{IL} = 0 \text{V}$ | 3.3 | -0.8 | |
| | | $C_L = 30 \text{ pF}, V_{IH} = 2.5 \text{V}, V_{IL} = 0 \text{V}$ | 2.5 | -0.6 | V |

Capacitance

| Symbol | Parameter | Conditions | Typical | Units |
|------------------|-------------------------------|---|---------|-------|
| C _{IN} | Input Capacitance | $V_{CC} = Open, V_I = 0V \text{ or } V_{CC}$ | 7 | pF |
| C _{I/O} | Input/Output Capacitance | $V_{CC} = 3.3V$, $V_I = 0V$ or V_{CC} | 8 | pF |
| C _{PD} | Power Dissipation Capacitance | $V_{CC} = 3.3V$, $V_{I} = 0V$ or V_{CC} , $f = 10$ MHz | 20 | pF |

Note 7: An external driver must sink at least the specified current to switch from HIGH-to-LOW.

AC LOADING and WAVEFORMS Generic for LCX Family

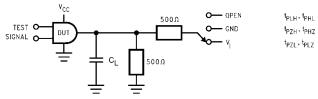
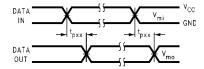
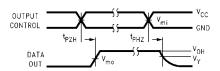


FIGURE 1. AC Test Circuit (C_L includes probe and jig capacitance)

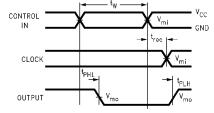
| Test | Switch |
|-------------------------------------|---|
| t _{PLH} , t _{PHL} | Open |
| t_{PZL} , t_{PLZ} | 6V at V_{CC} = 3.3 ± 0.3V, 2.7V and V_{CC} x 2 at V_{CC} = 2.5 ± 0.2V |
| t _{PZH} , t _{PHZ} | GND |



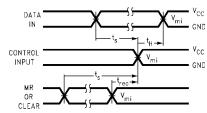
Waveform for Inverting and Non-Inverting Functions



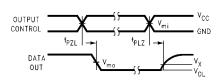
3-STATE Output High Enable and Disable Times for Logic



Propagation Delay. Pulse Width and \mathbf{t}_{rec} Waveforms



Setup Time, Hold Time and Recovery Time for Logic



3-STATE Output Low Enable and Disable Times for Logic

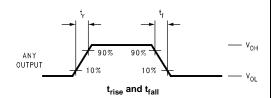
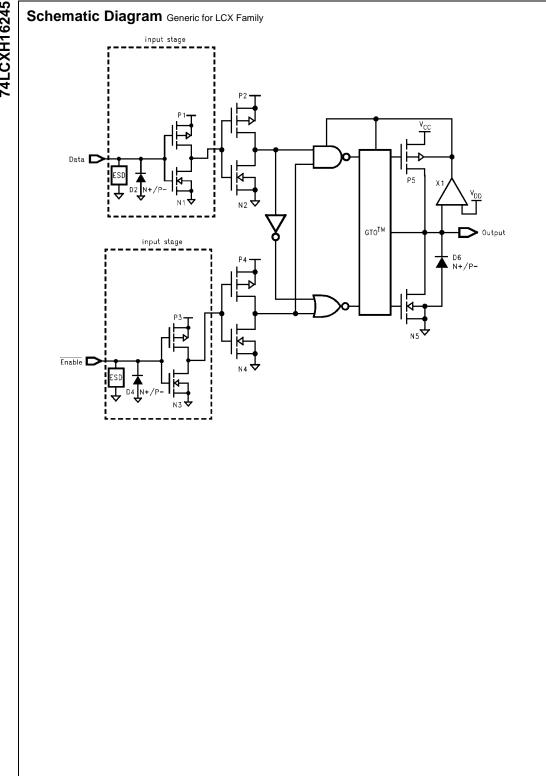
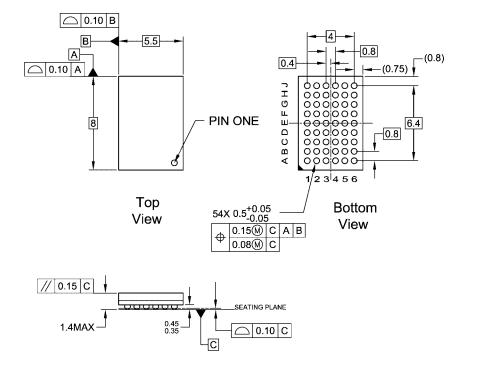


FIGURE 2. Waveforms (Input Characteristics; f =1MHz, t_r = t_f = 3ns)

| Symbol | V _{CC} | | |
|----------------|------------------------|------------------------|-------------------------|
| | $3.3V \pm 0.3V$ | 2.7V | 2.5V ± 0.2V |
| V_{mi} | 1.5V | 1.5V | V _{CC} /2 |
| V_{mo} | 1.5V | 1.5V | V _{CC} /2 |
| V _x | V _{OL} + 0.3V | V _{OL} + 0.3V | V _{OL} + 0.15V |
| V _v | V _{OH} – 0.3V | $V_{OH} - 0.3V$ | V _{OH} – 0.15V |



Physical Dimensions inches (millimeters) unless otherwise noted



NOTES:

- A. THIS PACKAGE CONFORMS TO JEDEC M0-205
- A. THIS PACKAGE CONFORMS TO JEDEC MI0-200

 B. ALL DIMENSIONS IN MILLIMETERS

 C. LAND PATTERN RECOMMENDATION: NSMD (Non Solder Mask Defined)

 .35MM DIA PADS WITH A SOLDERMASK OPENING OF .45MM CONCENTRIC TO PADS

 D. DRAWING CONFORMS TO ASME Y14.5M-1994

BGA54ArevD

54-Ball Fine-Pitch Ball Grid Array (FBGA), JEDEC MO-205, 5.5mm Wide Package Number BGA54A

Physical Dimensions inches (millimeters) unless otherwise noted (Continued) 12.50±0.10 0.40 TYP -B-99. 9.20 8.10 50. O.2 C B A ALL LEAD TIPS PIN #1 IDENT 0.50 LAND PATTERN RECOMMENDATION 0.1 C SEE DETAIL A 0.90+0.15 ALL LEAD TIPS 0.09-0.20 0.10±0.05 0.17-0.27 0.50 ♦ 0.13@ A BS CS 12.00' TOP & BOTTOM DIMENSIONS ARE IN MILLIMETERS R0.16 GAGE PLANE 0.25 NOTES: A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION ED, DATE 4/97. B. DIMENSIONS ARE IN MILLIMETERS. SEATING PLANE 0.60±0.10 1.00 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS. D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982. DETAIL A MTD48REVC

48-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 6.1mm Wide Package Number MTD48

Fairchild does not assume any responsibility for use of any circuitry described, no circuit patent licenses are implied and Fairchild reserves the right at any time without notice to change said circuitry and specifications.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

- Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in the labeling, can be reasonably expected to result in a significant injury to the user.
- A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

www.fairchildsemi.com

ON Semiconductor and in are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at www.onsemi.com/site/pdt/Patent-Marking.pdf. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and exp

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor 19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA Phone: 303-675-2175 or 800-344-3860 Toll Free USA/Canada Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81-3-5817-1050

ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative